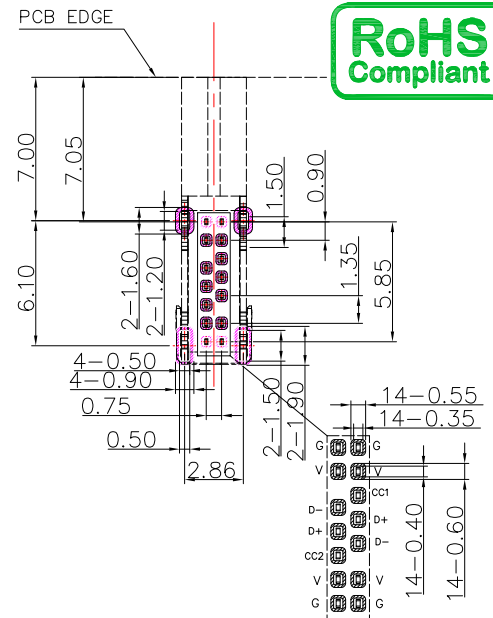
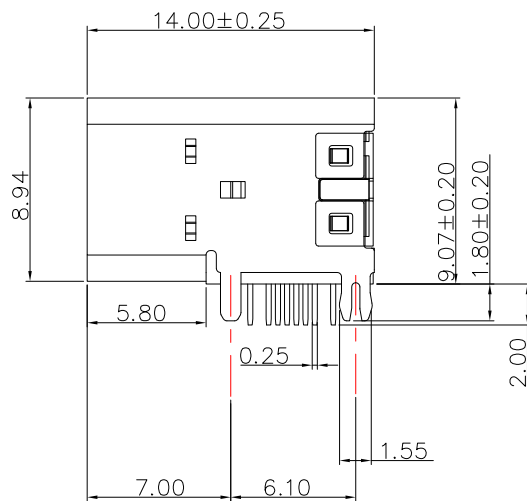
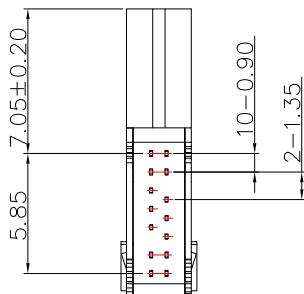
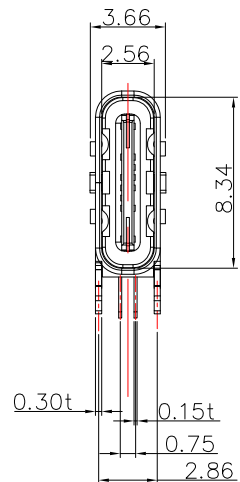
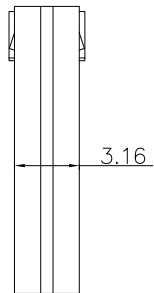




# SBC-140P-20x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



## RECOMMENDED P.C.B. LAYOUT

### SPECIFICATIONS

#### Electrical:

1. Dielectric Withstand Voltage: 100V AC
2. Contact Resistance: 40 mΩ Max
3. Insulation Resistance: 100 MΩ Min

#### Mechanical:

1. Connector Mate and Unmate Force
  - 1.1 Mate force: 5~20 N
  - 1.2 Unmate force: 8~20 N

#### Material:

1. Housing: High-Temp
2. Contact: Copper Alloy
3. Shell: SUS

#### Finish:

1. Contact: Plated Gold in Mating Area ;  
Tin Plated on Solder Balls ;  
Nickel under plated overall
2. Shell: Nickel under Plated surface layer



TOLERANCE UNLESS OTHERWISE STATED:

Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3°

3RD. ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	09/06/19
CHECKED BY:	DATE
Jacky Chen	09/06/19
APPROVED BY:	DATE
Tony Kao	09/06/19

MAT'L		TITLE	CONNECTOR
FINISH		MODLE	USB 3.1 側插母座 14 PIN
SCALE	1 : 1	DWG NO.	SBC-140P-20x-S242
SHEET NO.	1 of 1	PART NO.	SBC-140P-20x-S242
		SIZE	A4
		VER	R1

1	新增PCB LAYOUT尺寸	Jack	090619
ITEM NO.	DESCRIPTION	DRAWN	DATE